Efficient Computing for AI and Robotics: From Hardware Accelerators to Algorithm Design



Massachusetts Institute of Technology

In collaboration with Luca Carlone, Yu-Hsin Chen, Joel Emer, Sertac Karaman, Tushar Krishna, Peter Li, Fangchang Ma, Amr Suleiman, Diana Wofk, Nellie Wu, Tien-Ju Yang, Zhengdong Zhang

Slides available at <u>https://tinyurl.com/SzeMITDL2020</u>

Processing at "Edge" instead of the "Cloud"



Communication

Privacy

Latency

Computing Challenge for Self-Driving Cars

JACK STEWART TRANSPORTATION 02.06.18 08:00 AM

SELF-DRIVING CARS USE CRAZY AMOUNTS OF POWER, AND IT'S BECOMING A PROBLEM



Shelley, a self-driving Audi TT developed by Stanford University, uses the brains in the trunk to speed around a racetrack autonomously.

WIRED

(Feb 2018)

Cameras and radar generate ~6 gigabytes of data every 30 seconds.

Self-driving car prototypes use approximately 2,500 Watts of computing power.

Generates wasted heat and some prototypes need water-cooling!

Existing Processors Consume Too Much Power



< 1 Watt

> 10 Watts

Transistors Are Not Getting More Efficient



Slowdown of Moore's Law and **Dennard Scaling**

General purpose microprocessors are not getting faster or more efficient

Slowdown

Need specialized / domain-specific hardware for significant improvements in speed and energy efficiency

Efficient Computing with Cross-Layer Design



Systems



Architectures



Circuits



Pliī

Energy Dominated by Data Movement

Operation:	Energy (pJ)	Relative Energy Cost
8b Add	0.03	
16b Add	0.05	
32b Add	0.1	
16b FP Add	0.4	
32b FP Add	0.9	
8b Multiply	0.2	
32b Multiply	3.1	
16b FP Multiply	1.1	
32b FP Multiply	3.7	
32b SRAM Read (8KB)	5	
32b DRAM Read	640	

Memory access is **orders of magnitude** higher energy than compute

1 10 10² 10³ 10⁴

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Autonomous Navigation Uses a Lot of Data

Semantic Understanding

- High frame rate
- Large resolutions
- Data expansion

Geometric Understanding

• Growing map size



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[Pire, RAS 2017]

Visual-Inertial Localization

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Determines location/orientation of robot from images and IMU (also used by headset in Augmented Reality and Virtual Reality)



Localization

Localization at Under 25 mW

First chip that performs *complete* Visual-Inertial Odometry

Front-End for camera (Feature detection, tracking, and outlier elimination)

Front-End for IMU

(pre-integration of accelerometer and gyroscope data)

Back-End Optimization of Pose Graph

Consumes 684× and 1582× less energy than mobile and desktop CPUs, respectively



Technology	65nm CMOS	Supply	1 V
Chip area (mm ²)	4.0 x 5.0	Resolution	752x480
Core area (mm ²)	3.54 x 4.54	Camera rate	28 - 171 fps
Logic gates	2,043 kgates	Keyframe rate	16 - 90 fps
SRAM	854KB	Average Power	24 mW
VFE Frequency	62.5 MHz	GOPS	10.5 - 59.1
BE Frequency	83.3 MHz	GFLOPS	1-5.7



[Joint work with Sertac Karaman (AeroAstro)]

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[Zhang, RSS 2017], [Suleiman, VLSI-C 2018]

Key Methods to Reduce Data Size

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Navion: Fully integrated system – no off-chip processing or storage



Use **compression** and **exploit sparsity** to reduce memory down to 854kB

Navion Project Website: <u>http://navion.mit.edu</u>

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http://sze.mit.edu/
@eems_mit [Suleiman, VLSI-C 2018] Best Student Paper Award

Understanding the Environment

Depth Estimation



Semantic Segmentation



output layer input layer hidden layer State-of-the-art approaches use Deep Neural Networks, which require up to several hundred millions of operations and weights to compute! >100x more complex than video

compression

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Deep Neural Networks

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Deep Neural Networks (DNNs) have become a cornerstone of AI

Computer Vision



Game Play

Speech Recognition



Medical



Book on Efficient Processing of DNNs



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Part I Understanding Deep Neural Networks

Introduction Overview of Deep Neural Networks

Part II Design of Hardware for Processing DNNs

Key Metrics and Design Objectives Kernel Computation Designing DNN Accelerators Operation Mapping on Specialized Hardware

Part III Co-Design of DNN Hardware and Algorithms

Reducing Precision Exploiting Sparsity Designing Efficient DNN Models Advanced Technologies

https://tinyurl.com/EfficientDNNBook

Weighted Sums



¹⁶ High-Dimensional Convolution in CNN



Many Input Channels (C)

Define Shape for Each Layer



Output fmaps



N

F

Shape varies across layers

- **H** Height of input fmap (activations)
- **W** Width of input fmap (activations)
- **C** Number of 2-D input fmaps /filters (channels)
- **R** Height of 2-D filter (weights)
- **S** Width of 2-D filter (weights)
- **M** Number of 2-D output fmaps (channels)
- **E** Height of output fmap (activations)
- **F** Width of output fmap (activations)

N – Number of input fmaps/output fmaps (batch size)

Popular DNN Models

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Metrics	LeNet-5	AlexNet	VGG-16	GoogLeNet (v1)	ResNet-50	EfficientNet-B4
Top-5 error (ImageNet)	n/a	16.4	7.4	6.7	5.3	3.7*
Input Size	28x28	227x227	224x224	224x224	224x224	380x380
# of CONV Layers	2	5	16	21 (depth)	49	96
# of Weights	2.6k	2.3M	14.7M	6.0M	23.5M	14M
# of MACs	283k	666M	15.3G	1.43G	3.86G	4.4G
# of FC layers	2	3	3	1	1	65**
# of Weights	58k	58.6M	124M	1M	2M	4.9M
# of MACs	58k	58.6M	124M	1M	2M	4.9M
Total Weights	60k	61M	138M	7M	25.5M	19 M
Total MACs	341k	724M	15.5G	1.43G	3.9G	4.4G
Reference	Lecun , <i>PIEEE</i> 1998	Krizhevsky, NeurIPS 2012	Simonyan , <i>ICLR</i> 2015	Szegedy , CVPR 2015	He , CVPR 2016	Tan , <i>ICML</i> 2019

DNN models getting larger and deeper

* Does not include multi-crop and ensemble

** Increase in FC layers due to squeeze-and-excitation layers (much smaller than FC layers for classification)

Properties We Can Leverage

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- Operations exhibit high parallelism
 → high throughput possible
- Memory Access is the Bottleneck



Worst Case: all memory R/W are **DRAM** accesses

Example: AlexNet has **724M** MACs → **2896M** DRAM accesses required

²⁰ **Properties We Can Leverage**

- Operations exhibit high parallelism
 → high throughput possible
- Input data reuse opportunities (up to 500x)



Exploit Data Reuse at Low-Cost Memories



Specialized hardware with small (< 1kB) low cost memory near compute



* measured from a commercial 65nm process

Weight Stationary (WS)



- Minimize weight read energy consumption
 - maximize convolutional and filter reuse of weights
- Broadcast activations and accumulate partial sums spatially across the PE array
- Examples: TPU [Jouppi, /SCA 2017], NVDLA

Output Stationary (OS)



- Minimize partial sum R/W energy consumption
 - maximize local accumulation
- Broadcast/Multicast filter weights and reuse activations spatially across the PE array
- Examples: [Moons, VLS/ 2016], [Thinker, VLS/ 2017]

Row Stationary Dataflow



- Maximize row convolutional reuse in RF
 - Keep a filter row and fmap sliding window in RF
- Maximize row psum accumulation in RF



Row Stationary Dataflow

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Dataflow Comparison: CONV Layers



²⁷ Deep Neural Networks at Under 0.3W



[Chen, /SSCC 2016]

Results for AlexNet

Exploits data reuse for **100x** reduction in memory accesses from global buffer and **1400x** reduction in memory accesses from off-chip DRAM

Overall >10x energy reduction compared to a mobile GPU (Nvidia TK1)

Eyeriss Project Website: <u>http://eyeriss.mit.edu</u>

²⁸ Features: Energy vs. Accuracy



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[Suleiman, ISCAS 2017]

Energy-Efficient Processing of DNNs

A significant amount of algorithm and hardware research on energy-efficient processing of DNNs





Efficient Processing of Deep Neural Networks: A Tutorial and Survey System Scaling With Nanostructured Power and RF Components Nonorthogonal Multiple Access for 5G and Beyond Point of View: Beyond Smart Crid—A Cyber–Physical–Social System in Energy Future Scanning Our Past: Materials Science, Instrument Knowledge, and the Power Source Renaissance



V. Sze, Y.-H. Chen, T-J. Yang, J. Emer, **"Efficient Processing of Deep Neural Networks: A Tutorial and Survey**," Proceedings of the IEEE, Dec. 2017

We identified various limitations to existing approaches

Design of Efficient DNN Algorithms

Popular efficient DNN algorithm approaches

Network Pruning



... also reduced precision

- Focus on reducing number of MACs and weights
- Does it translate to energy savings and reduced latency?

Efficient Network Architectures

Number of MACs and Weights are Not Good Proxies



of operations (MACs) does not approximate

Source: Google (<u>https://ai.googleblog.com/2018/04/introducing-cvpr-2018-on-device-visual.html</u>)

of weights *alone* is not a good metric for energy (All data types should be considered)



Energy-Aware Pruning

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Directly target energy and incorporate it into the optimization of DNNs to provide greater energy savings

- Sort layers based on energy and prune layers that consume the most energy first
- Energy-aware pruning reduces AlexNet energy by 3.7x w/ similar accuracy
- Outperforms magnitude-based pruning by **1.7x**

[Yang, CVPR 2017]



Pruned models available at

http://eyeriss.mit.edu/energy.html

Normalized Energy (AlexNet)

NetAdapt: Platform-Aware DNN Adaptation

- Automatically adapt DNN to a mobile platform to reach a target latency or energy budget
- Use empirical measurements to guide optimization (avoid modeling of tool chain or platform architecture)
- Few hyperparameters to reduce tuning effort
- >1.7x speed up on MobileNet w/ similar accuracy



http://netadapt.mit.edu

[In collaboration with Google's Mobile Vision Team]

[**Yang**, *ECCV* 2018]

FastDepth: Fast Monocular Depth Estimation

Depth estimation from a single RGB image desirable, due to the relatively low cost and size of monocular cameras.









~40fps on an iPhone

Models available at <u>http://fastdepth.mit.edu</u>

[Joint work with Sertac Karaman]

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[Wofk*, Ma*, *ICRA* 2019]

Many Efficient DNN Design Approaches



Network Pruning

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[Chen*, Yang*, SysML 2018] Vivienne Sze () <u>http://sze.mit.edu/</u> () @eems_mit

Existing DNN Architectures

- Specialized DNN hardware often rely on certain properties of DNN in order to achieve high energy-efficiency
- **Example:** Reduce memory access by amortizing across MAC array


Limitation of Existing DNN Architectures

- Example: Reuse and array utilization depends on # of channels, feature map/batch size
 - Not efficient across all network architectures (e.g., compact DNNs)



Limitation of Existing DNN Architectures

- Example: Reuse and array utilization depends on # of channels, feature map/batch size
 - Not efficient across all network architectures (e.g., compact DNNs)



Limitation of Existing DNN Architectures

- Example: Reuse and array utilization depends on # of channels, feature map/batch size
 - Not efficient across all network architectures (e.g., compact DNNs)
 - Less efficient as array scales up in size
 - Can be challenging to exploit sparsity



Need Flexible Dataflow & Mapping

• Use flexible dataflow (**Row Stationary**) to exploit reuse in any dimension of DNN to increase energy efficiency and array utilization



Example: Depth-wise layer

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[**Chen**, *JETCAS* 2019]

41 Need Flexible NoC for Varying Reuse

- When reuse available, need **multicast** to exploit spatial data reuse for energy efficiency and high array utilization
- When reuse not available, need **unicast** for high BW for weights for FC and weights & activations for high PE utilization
- An all-to-all satisfies above but too expensive and not scalable



42 Hierarchical Mesh



[**Chen**, *JETCAS* 2019]

Eyeriss v2: Balancing Flexibility and Efficiency

- Uses a flexible hierarchical mesh on-chip network to efficiently support
 - Wide range of filter shapes
 - Different layers

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- Wide range of sparsity
- Scalable architecture

Over an order of magnitude faster and more energy efficient than Eyeriss v1



Speed up over Eyeriss v1 scales with number of PEs

# of PEs	256	1024	16384
AlexNet	17.9x	71.5x	1086.7x
GoogLeNet	10.4x	37.8x	448.8x
MobileNet	15.7x	57.9x	873.0x

[Joint work with Joel Emer]

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[Chen, arXiv 2019: https://arxiv.org/abs/1807.07928]

DNN Accelerator Evaluation Tools

- Require systematic way to
 - Evaluate and compare DNN accelerators
 - Rapidly explore design space
- Accelergy [Wu, ICCAD 2019]

- Early stage estimation tool at the architecture level
 - Estimate energy based on architecture level components (e.g., # of PEs, memory size, on-chip network)
- Evaluate architecture level impact of emerging devices
 - Plug-ins for different technologies
- Timeloop [Parashar, ISPASS 2019]
 - DNN mapping tool
 - Performance Simulator \rightarrow Action counts

Accelergy Estimation Validation

- Validation on Eyeriss [Chen, ISSCC 2016]
 - Achieves 95% accuracy compared to post-layout simulations
 - Can accurately captures energy breakdown at different granularities

Open-source code available at: http://accelergy.mit.edu

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Open-source code available at: <u>http://accelergy.mit.edu</u>

Compound Component Description

Open-source code available at: <u>http://accelergy.mit.edu</u>

| Plug-ins for Fine-Grain Action Energy Estimation

- External energy/area models that accurately reflect the properties of a macro
 - e.g., multiplier with zero-gating

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Energy characterizations of the zero-gated multiplier (normalized to idle) ground truth Accelergy 0.25 23.0 Energy Consumption (uJ) 0.20 16.8 0.15 ~20x 0.10 1.3 0.05 Random Gated Reused 0.00 PE4 PE1 PE3 PE5 PE6 PE8 PE0 PE2 PE7 multiply multiply multiply PEs that process data of different sparsity

With the characterization provided in the plug-in, we can capture the energy savings for sparse workloads

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[**Wu**, *ICCAD* 2019]

PnR simulations

In-Memory Computing (IMC*)

Activation is input voltage (V_i) Weight is resistor conductance (G_i)

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- Reduce data movement by moving compute into memory
- Compute MAC with memory storage element

Analog Compute

- Activations, weights and/or partial sums are encoded with analog voltage, current, or resistance
- Increased sensitivity to circuit non-idealities
- A/D and D/A circuits to interface with digital domain
- Leverage emerging memory device technology

In-Memory Computing (IMC)

- Implement as matrix-vector multiply
 - Typically, matrix composed of stored weights and vector composed of input activations
- Reduce weight data movement by moving compute into the memory
 - Perform MAC with storage element or in peripheral circuits
 - Read out partial sums rather than weights → fewer accesses through peripheral circuits
- Increase weight bandwidth

- Multiple weights accessed in parallel to keep MACs busy (high utilization)
- Increase amount of parallel MACs
 - Storage element can be higher area density than digital MAC
 - Reduce routing capacitance

Accelergy for IMC

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Open-source code available at: <u>http://accelergy.mit.edu</u>

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[**Wu**, *ISPASS* 2020]

Accelergy for IMC

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Accelergy + Timeloop Tutorial

Tutorial material available at http://accelergy.mit.edu/tutorial.html Includes videos and hands-on exercises

Designing DNNs for IMC

- Designing DNNs for IMC may differ from DNNs for digital processors
- Highest accuracy DNN on digital processor may be different on IMC
 - Accuracy drops based on robustness to nonidealities
- Reducing number of weights is less desirable
 - Since IMC is weight stationary, may be better to reduce number of activations
 - IMC tend to have larger arrays → fewer weights may lead to low utilization on IMC

Book Chapter on In-Memory Computing

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CHAPTER 10

Advanced Technologies

As highlighted throughout the previous chapters, data movement dominates energy consumption. The energy is consumed both in the access to the memory as well as the transfer of the data. The associated physical factors also limit the bandwidth available to deliver data between memory and compute, and thus limits the throughput of the overall system. This is commonly referred to by computer architects as the "memory wall."¹

To address the challenges associated with data movement, there have been various efforts to bring compute and memory closer together. Chapters 5 and 6 primarily focus on how to design spatial architectures that distribute the on-chip memory closer to the computation (e.g., scratch pad memory in the PE). This chapter will describe various other architectures that use advanced memory, process, and fabrication technologies to bring the compute and memory together.

First, we will describe efforts to bring the off-chip high-density memory (e.g., DRAM) closer to the computation. These approaches are often referred to as *processing near memory* or *near-data processing*, and include memory technologies such as embedded DRAM and 3-D stacked DRAM.

Next, we will describe efforts to integrate the computation *into* the memory itself. These approaches are often referred to as *processing in memory* or *in-memory computing*, and include memory technologies such as Static Random Access Memories (SRAM), Dynamic Random Access Memories (DRAM), and emerging non-volatile memory (NVM). Since these approaches rely on mixed-signal circuit design to enable processing in the analog domain, we will also discuss the design challenges related to handling the increased sensitivity to circuit and device non-idealities (e.g., nonlinearity, process and temperature variations), as well as the impact on area density, which is critical for memory.

Significant data movement also occurs between the sensor that collects the data and the DNN processor. The same principles that are used to bring compute near the memory, where the weights are stored, can be used to bring the compute *near* the sensor, where the input data is collected. Therefore, we will also discuss how to integrate some of the compute *into* the sensor.

Finally, since photons travel much faster than electrons and the cost of moving a photon can be *independent* of distance, processing in the optical domain using light may provide significant improvements in energy efficiency and throughput over the electrical domain. Accordingly, we will conclude this chapter by discussing the recent work that performs DNN processing in the optical domain, referred to as *Optical Neural Networks*.

¹Specifically, the memory wall refers to data moving between the off-chip memory (e.g., DRAM) and the processor.

Many Design Considerations for In-Memory Computing

- Number of Storage Elements per Weight
- Array Size
- Number of Rows Activated in Parallel
- Number of Columns Activated in Parallel
- Time to Deliver Input
- Time to Compute MAC

Tradeoffs between energy efficiency, throughput, area density, and accuracy, which *reduce the achievable gains over conventional architectures*

Available on DNN tutorial website http://eyeriss.mit.edu/tutorial.html

Where to Go Next: Planning and Mapping

Robot Exploration

Where to Go Next: Planning and Mapping

Robot Exploration: Decide where to go by computing Shannon Mutual Information

Experimental Results (4x Real Time)

Occupancy map with planned path using RRT* (compute MI on all possible paths)

MI surface

Exploration with a mini race car using motion capture for localization

Building Hardware Accelerator to Compute MI

Motivation: Compute MI faster for faster exploration!

$$I(M;Z) = \sum_{j=1}^{n} \sum_{k=j-\Delta}^{j+\Delta} P(e_j) C_k G_{k,j}$$

Fast Shannon Mutual Information (FSMI) [**Zhang**, *ICRA* 2019]

Algorithm is *embarrassingly* parallel!

High throughput *should* be possible with multiple processing elements (PE)

Challenge is Data Delivery to All PEs

Power consumption of memory scales with number of ports. Low power SRAM limited to two-ports!

Data delivery, specifically memory bandwidth, limits the throughput (not compute)

Proposed Accelerator Architecture

Increasing memory bandwidth (read ports) by partitioning the map storage into multiple banks

Proposed architecture includes

- 1) Memory banking pattern that minimizes memory access conflicts among all PEs
- 2) Efficient arbiter that quickly identifies and resolves memory access conflicts among all PEs

Memory Access Pattern

- Design a **fixed** banking pattern that minimizes the number of memory access collisions.
- Challenge: memory access pattern is dependent on the scan location and sensor angle.

Memory access pattern at every cycle

- The number denotes the order of memory access in each PE.
- During every cycle, PEs access the map locations in the same column or row.

Memory Access Pattern

- Design a **fixed** banking pattern that minimizes the number of memory access collisions.
- Challenge: memory access pattern is dependent on the scan location and sensor angle.

Memory access pattern at location B

⁷⁰ Naïve Memory Banking Pattern

Memory access pattern at every cycle

Challenge: memory access pattern is scan location and sensor angle dependent.

S E 6 7 8

PEs read the map at the same row or column every cycle

Vertical Banking Pattern

Conflicts when same column

Proposed Memory Banking Pattern

Challenge: memory access pattern is scan location and sensor angle dependent.

Memory access pattern at every cycle

PEs read the map at the same row or column every cycle

Diagonal Banking Pattern

Reduced conflicts across banks

Experimental Results

Specialized banking, efficient memory arbiter and packing multiple values at each address results in throughput **within 94% of theoretical limit** (unlimited bandwidth)

Compute MI for an **entire map** of 20m x 20m at 0.1m resolution **in under a second** on a ZC706 FPGA (100x faster than CPU at 10x lower power)
Generalize to a Class of Banking Patterns

• Latin-square banking tile: cells in each column and row is assigned to different banks



We **rigorously proved** that Latin-square tiles usage minimizes read conflicts between PEs

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- Efficient computing is critical for advancing the progress of AI & autonomous robots
 → Critical step to making AI & autonomy ubiquitous!
- In order to meet computing demands in terms of power and speed, need to redesign computing hardware from the ground up → Focus on data movement!
- Specialized hardware creates new opportunities for the co-design of algorithms and hardware → Innovation opportunities for the future of AI & robotics!



Acknowledgements

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Joel Emer



Sertac Karaman

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Low-Energy Autonomy and Navigation (LEAN) Group

LEAN	HOME	TEAM	RESEARCH	PUBLICATIONS	PRESS	RECOGNITION
						-

A broad range of next-generation applications will be enabled by low-energy, miniature mobile robotics including insect-size flapping wing robots that can help with search and rescue, chip-size satellites that can explore nearby stars, and blimps that can stay in the air for years to provide communication services in remote locations. While the low-energy, miniature actuation, and sensing systems have already been developed in many of these cases, the processors currently used to run the algorithms for autonomous navigation are still energy-hungry. Our research addresses this challenge as well as brings together the robotics and hardware design communities.

We enable efficient computing on various key modules of other autonomous navigation systems including perception, localization, exploration and planning. We also consider the overall system by considering the energy cost of computing in conjunction with actuation and sensing.



Motion Planning

Many motion planning and control algorithms aim to design trajectories and controllers that minimize actuation energy. However, in low-energy robotics, computing such trajectories and controls themselves may consume a large amount of energy. We develop algorithms that optimize this trade-off.



Mutual Information for Exploration

Computing mutual information between the map and future measurements is critical to efficient exploration. Unfortunately, mutual information computation is computationally very challenging. We develop new algorithms and hardware for efficient computation of mutual information, and demonstrate real-time computation for the whole map in a reasonably-sized map.



Depth Sensing and Perception

Depth sensing is a critical function for robotic tasks such as localization, mapping and obstacle detection. State-of-the-art single-view depth estimation algorithms are based on fairly complex deep neural networks that are too slow for real-time inference on an embedded platform, for instance, mounted on a micro aerial vehicle. We address the problem of fast depth estimation on embedded systems.



Localization and Mapping

Autonomous navigation of miniaturized robots (e.g., nano/pico aerial vehicles) is currently a grand challenge for robotics research, due to the need for processing a large amount of sensor data (e.g., camera frames) with limited on-board computational resources. We focus on the design of a visual-inertial odometry (VIO) system in which the robot estimates its ego-motion (and a landmark-based map) from on-board camera and IMU data.



Group Website: http://lean.mit.edu

Book on Efficient Processing of DNNs



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Excerpts of Book

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CHAPTER 3 Key Metrics and Design **Objectives**

Over the past few years, there has been a significant amount of research on efficient processing of DNNs. Accordingly, it is important to discuss the key metrics that one should consider when comparing and evaluating the strengths and weaknesses of different designs and proposed techniques and that should be incorporated into design considerations. While efficiency is often only associated with the number of operations per second per Watt (e.g., floating-point operations per second per Watt as FLOPS/W or tera-operations per second per Watt as TOPS/W), it is actually composed of many more metrics including accuracy, throughput, latency, energy consumption, power consumption, cost, flexibility, and scalability. Reporting a comprehensive set of these metrics is important in order to provide a complete picture of the trade-offs made by a proposed design or technique.

In this chapter, we will

- · discuss the importance of each of these metrics;
- breakdown the factors that affect each metric. When feasible, present equations that describe the relationship between the factors and the metrics;
- describe how these metrics can be incorporated into design considerations for both the DNN hardware and the DNN model (i.e., workload); and
- · specify what should be reported for a given metric to enable proper evaluation.

Finally, we will provide a case study on how one might bring all these metrics together for a holistic evaluation of a given approach. But first, we will discuss each of the metrics.

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3.1 ACCURACY

Accuracy is used to indicate the quality of the result for a given task. The fact that DNNs car achieve state-of-the-art accuracy on a wide range of tasks is one of the key reas popularity and wide use of DNNs today. The units used to measure accuracy task. For instance, for image classification, accuracy is reported as the percent classified images, while for object detection, accuracy is reported as the mean a (mAP), which is related to the trade off between the true positive rate and false

CHAPTER 10

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Available on DNN tutorial website http://eyeriss.mit.edu/tutorial.html

ISSCC 2020 TUTORIAL

Vivienne Sze, Yu-Hsin Chen, Tien-Ju Yang, and Joel S. Emer ImageNet

How to **Evaluate Deep Neural Network Processors**

TOPS/W (alone) Considered Harmful



and the DNN models themselves. We

also describe specific metrics that can

aluate and compare ex-

ns beyond the commonly

rations per second per

. This article is based on

How to Understand and

en Learning Processors"

en at the 2020 Interna-

works [36]. Motivation and Background industry. This article aims to highlight Over the past few years, there has the key concepts required to evaluate been a significant amount of research and compare these DNN processors. on enabling the efficient processing We discuss existing challenges, such of DNNs. The challenge of efficient as the flexibility and scalability need-DNN processing depends on balanced to support a wide range of neural ing multiple objectives. networks, as well as design consider ations for both the DNN processors

high performance (including accuracy) and efficiency (including (Doct) s enough flexibility to cater to a wide and rapidly changing range of workloads

tional Solid-State Circuits Conference,

as well as excerpts from the book. FF-

ficient Processing of Deep Neural Net-

good integration with existing software frameworks. DNN computations are composed of several processing layers (Figure 1) where for many layers the main computation is a weighted sum; in other words, the main computation for DNN processing is often a

multiply-accumulate (MAC) opera tion. The arrangement of the MAC operations within a layer is defined by the layer shape; for instance, Table 1 and Figure 2 highlight the shape parameters for lavers used in convolutional neural networks (CNNs), a popular type of DNN. Because the shape parameters can vary across lavers. DNNs come in a wide variety of shapes and sizes, depending on the application. (The DNN research community often refers to the shape and size of a DNN as its network architecture. However, to avoid confusion with the use of the word architecture by the hardware community, we talk about DNN models and their shape and size in this article.) This variety is one of the motivations for flexibility, and it causes the objectives listed previously to be highly interrelated

MNIST

Figure 3 illustrates the hardware architecture of a typical DNN processor, which is composed of an array

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Additional Resources

Talks and Tutorial Available Online

https://tinyurl.com/SzeMITDL2020









YouTube Channel EEMS Group – PI: Vivienne Sze

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Vivienne Sze I <u>http://sze.mit.edu/</u> I @eems_mit



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